

August 1991

Features

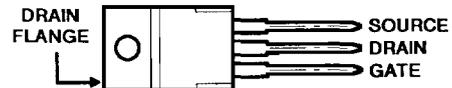
- 2A, 180V and 200V
- $r_{DS(on)} = 3.5\Omega$
- SOA is Power-Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device

Description

The RFP2N18 and RFP2N20 are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

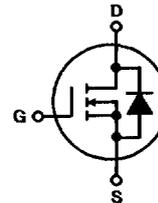
The RFP series types are supplied in the JEDEC TO-220AB plastic package.

Package

 TO-220AB
TOP VIEW


Terminal Diagram

N-CHANNEL ENHANCEMENT MODE



Absolute Maximum Ratings ($T_C = +25^\circ\text{C}$), Unless Otherwise Specified

| | RFP2N18 | RFP2N20 | UNITS |
|--|-------------|-------------|---------------------|
| Drain-Source Voltage | 180 | 200 | V |
| Drain-Gate Voltage ($R_{GS} = 1M\Omega$) | 180 | 200 | V |
| Continuous Drain Current | 2 | 2 | A |
| Pulsed Drain Current | 5 | 5 | A |
| Gate-Source Voltage | ± 20 | ± 20 | V |
| Maximum Power Dissipation | | | |
| $T_C = +25^\circ\text{C}$ | 25 | 25 | W |
| Derate Above $T_C = +25^\circ\text{C}$ | 0.2 | 0.2 | W/ $^\circ\text{C}$ |
| Operating and Storage Temperature | -55 to +150 | -55 to +150 | $^\circ\text{C}$ |

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 N-CHANNEL
POWER MOSFETS

Specifications RFP2N18, RFP2N20

Electrical Characteristics ($T_C = +25^\circ\text{C}$), Unless Otherwise Specified

| CHARACTERISTIC | SYMBOLS | TEST CONDITIONS | LIMITS | | | | UNITS |
|-------------------------------------|-----------------|---|----------|-----|----------|-----|---------------|
| | | | RFP2N18 | | RFP2N20 | | |
| | | | MIN | MAX | MIN | MAX | |
| Drain-Source Breakdown Voltage | V_{DSS} | $I_D = 1\text{mA}, V_{GS} = 0$ | 180 | - | 200 | - | V |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{GS} = V_{DS}, I_D = 2\text{mA}$ | 2 | 4 | 2 | 4 | V |
| Zero-Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 145\text{V}$ | - | 1 | - | - | μA |
| | | $V_{DS} = 160\text{V}$ | - | - | - | 1 | μA |
| | | $T_C = +125^\circ\text{C}$ $V_{DS} = 145\text{V}$ | - | 50 | - | - | μA |
| | | $V_{DS} = 160\text{V}$ | - | - | - | 50 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS} = \pm 20\text{V}, V_{DS} = 0$ | - | 100 | - | 100 | nA |
| Drain-Source On-Voltage | $V_{DS(on)}^*$ | $I_D = 1\text{A}, V_{GS} = 10\text{V}$ | - | 3.5 | - | 3.5 | V |
| | | $I_D = 2\text{A}, V_{GS} = 10\text{V}$ | - | 8.0 | - | 8.0 | V |
| Static Drain-Source On Resistance | $r_{DS(on)}^*$ | $I_D = 1\text{A}, V_{GS} = 10\text{V}$ | - | 3.5 | - | 3.5 | Ω |
| Forward Transconductance | g_{fs}^* | $I_D = 1\text{A}, V_{DS} = 10\text{V}$ | 400 | - | 400 | - | S ({}) |
| Input Capacitance | C_{ISS} | $V_{GS} = 0\text{V}, V_{DS} = 25\text{V}$ $f = 1\text{MHz}$ | - | 200 | - | 200 | pF |
| Output Capacitance | C_{OSS} | | - | 60 | - | 60 | pF |
| Reverse-Transfer Capacitance | C_{RSS} | | - | 25 | - | 25 | pF |
| Turn-On Delay Time | $t_{d(on)}$ | $I_D = 1\text{A}, V_{DD} = 100\text{V}$ $R_{GEN} = R_{GS} = 50\Omega$ $V_{GS} = 10\text{V}$ | 15 (typ) | 25 | 15 (typ) | 25 | ns |
| Rise Time | t_r | | 20 (typ) | 30 | 20 (typ) | 30 | ns |
| Turn-Off Delay Time | $t_{d(off)}$ | | 25 (typ) | 40 | 25 (typ) | 40 | ns |
| Fall Time | t_f | | 15 (typ) | 25 | 15 (typ) | 25 | ns |
| Thermal Resistance Junction-to-Case | $R_{\theta JC}$ | | | - | 5 | - | 5 |

Source-Drain Diode Ratings and Characteristics

| CHARACTERISTIC | SYMBOLS | TEST CONDITIONS | LIMITS | | | | UNITS |
|-----------------------------|------------|---|-----------|-----------|-----------|-----------|-------|
| | | | RFP2N18 | | RFP2N20 | | |
| | | | MIN | MAX | MIN | MAX | |
| Diode Forward Voltage | V_{SD}^* | $I_{SD} = -1\text{A}$ | - | 1.4 | - | 1.4 | V |
| Diode Reverse Recovery Time | t_{rr} | $I_F = 2\text{A}$ $dI_F/dt = 50\text{A}/\mu\text{s}$ | 200 (typ) | 200 (typ) | 200 (typ) | 200 (typ) | ns |

* Pulsed: Pulse duration = 300 μs max., duty cycle = 2%.

RFP2N18, RFP2N20

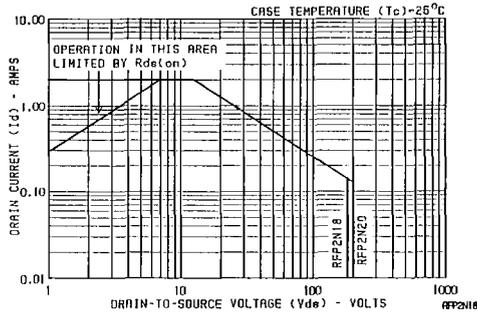


Fig. 1 - Maximum operating areas for all types.

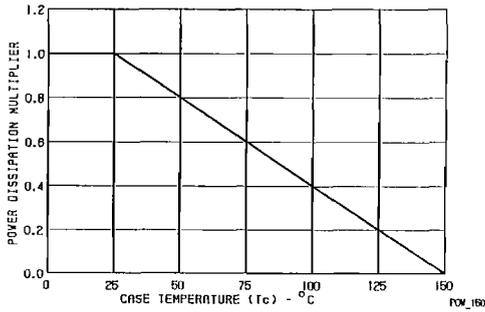


Fig. 2 - Normalized power dissipation vs temperature derating curve.

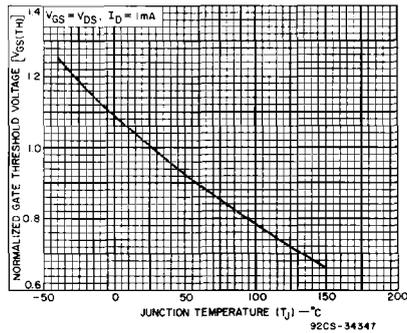


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature for all types.

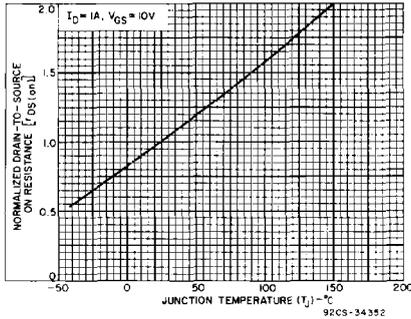


Fig. 4 - Normalized drain-to-source on resistance to junction temperature for all types.

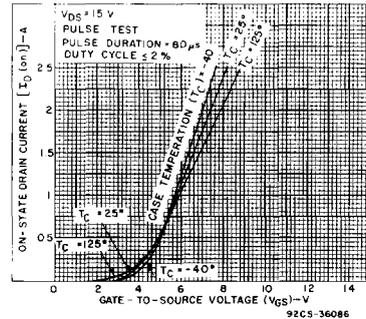


Fig. 5 - Typical transfer characteristics for all types.

RFP2N18, RFP2N20

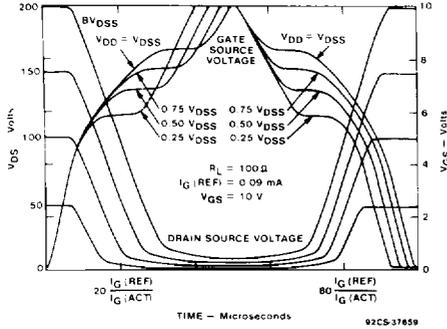


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to Harris application notes AN-7254 and AN-7260.

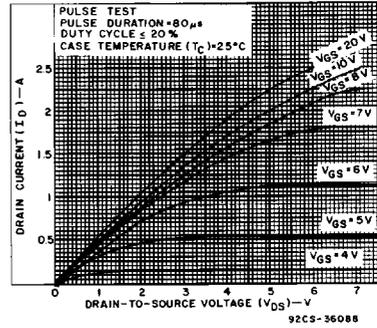


Fig. 7 - Typical saturation characteristics for all types.

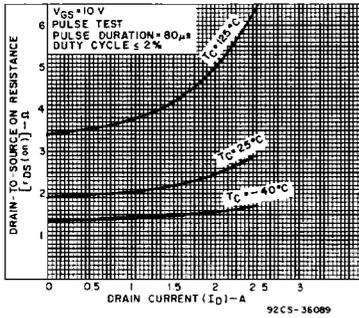


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

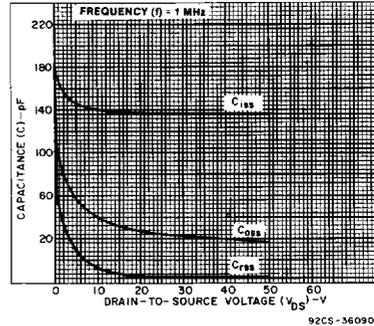


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

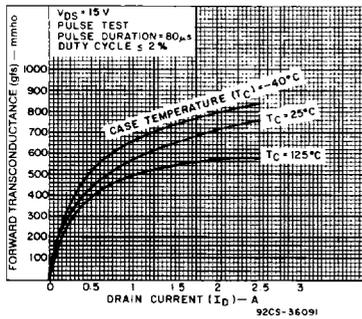


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

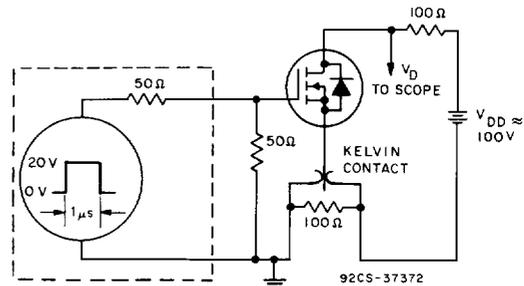


Fig. 11 - Switching Time Test Circuit.